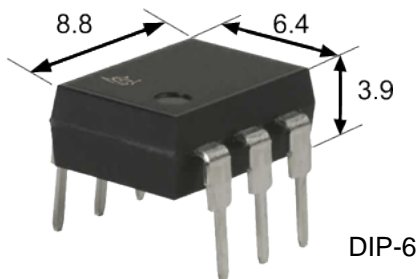
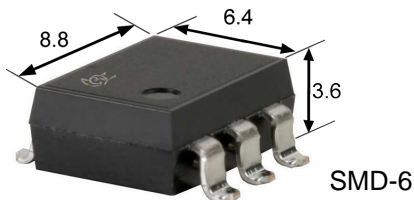



Features

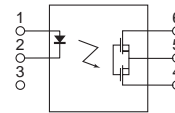
- Low driver power requirements (TTL/CMOS Compatible)
- No moving parts
- High reliability
- Arc-Free with no snubbing circuits
- 3750Vrms Input/Output isolation

Applications

- Telecommunications (PC, Electronic notepad)
- Measuring and Testing equipment
- Industrial control
- Security equipments
- High speed inspection machine


DIP-6

SMD-6

(Unit: mm)



1. LED Anode
2. LED Cathode
4. Drain (MOS FET)
5. Source (MOS FET)
6. Drain (MOS FET)

TYPES

Category	Output rating		Package	Part No.	Packing quantity
	Load voltage	Load current			
AC/DC	1500V	45mA	DIP6	APV258E	50pcs/tube
			SMD6	APV258EH	1000pcs/reel

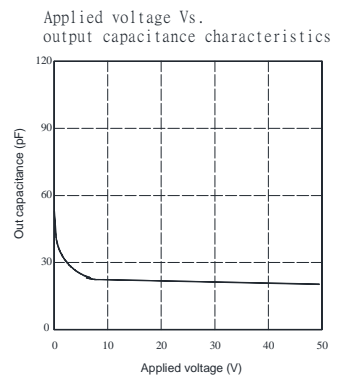
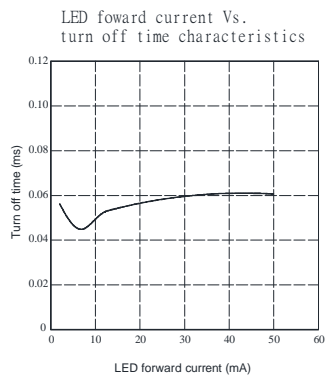
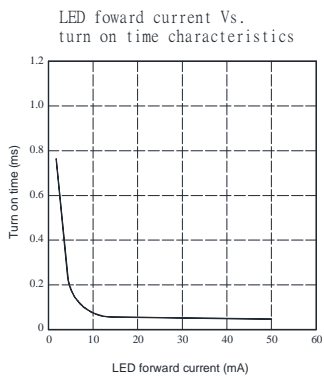
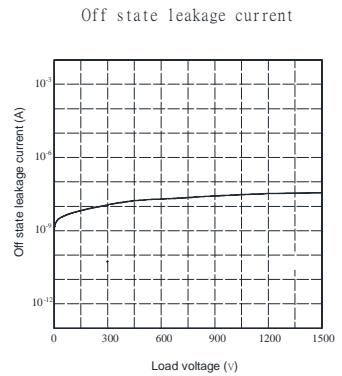
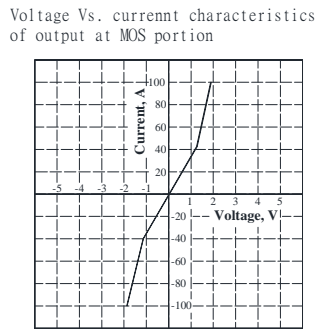
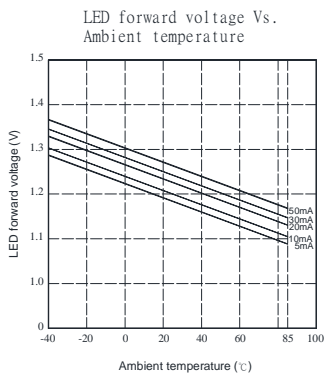
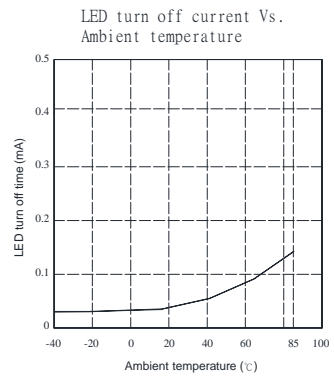
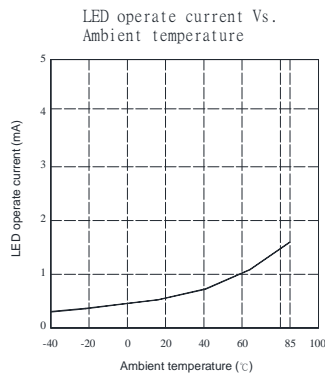
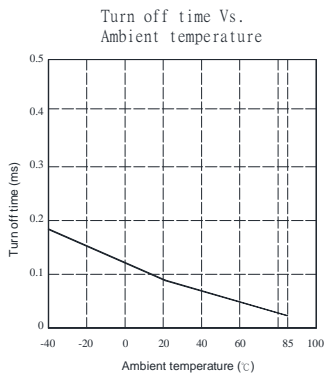
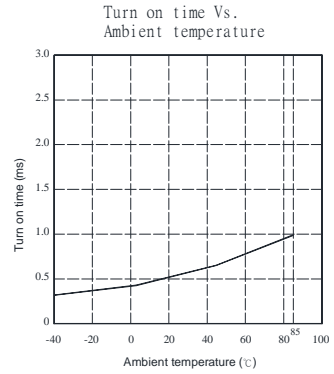
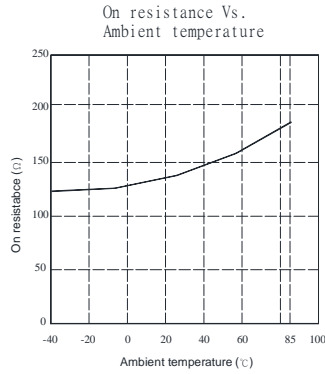
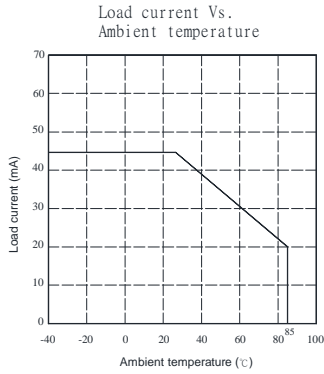
Absolute Maximum Ratings (Ambient Temperature: 25°C)

Item		Symbol	Value	Units	Note
Input	Continuous LED Current	I _F	50	mA	
	Peak LED Current	I _{FP}	1000	mA	f=100Hz, duty=1%
	LED Reverse Voltage	V _R	5	V	
	Input Power Dissipation	P _{In}	75	mW	
Output	Load Voltage	V _L	1500	V(AC peak or DC)	
	Load Current	I _L	45	mA	A (AC)
			50	mA	B (DC)
			75	mA	C (DC)
	Peak Load Current	I _{Peak}	180	mA	100ms(1 pulse)
Output Power Dissipation	P _{out}	450	mW		
Total Power Dissipation		P _T	500	mW	
I/O Breakdown Voltage		V _{I/O}	3750	V _{rms}	RH=60%, 1min
I/O Breakdown Voltage(Suffix-V)		V _{I/O}	5000	V _{rms}	RH=60%, 1min
Operating Temperature		T _{opr}	-40 to +85	°C	
Storage Temperature		T _{stg}	-40 to +100	°C	
Pin Soldering Temperature		T _{sol}	260	°C	10 sec max.

Electrical Specifications (Ambient Temperature: 25°C)

Item		Symbol	MIN.	TYP.	MAX.	Units	Conditions
Input	LED Forward Voltage	V _F		1.2	1.5	V	I _F =10mA
	Operation LED Current	I _{F on}		0.8	5.0	mA	
	Recovery LED Current	I _{F off}		0.35	0.8	mA	
	Recovery LED Voltage	V _{F off}	0.7			V	
Output	On-Resistance	R _{on}		130	200	Ω	I _F =10mA, I _L = Rating, Time to flow is within 1 sec.
				220	300	Ω	I _F =10mA, I _L <= 5mA
	Off-State Leakage Current	I _{Leak}			10	uA	V _L =Rating
	Output Capacitance	C _{out}		58		pF	V _L =0, f=1MHz
Transmis sion	Turn-On Time	T _{on}		0.3	1.0	ms	I _F =10mA, I _L =Rating
	Turn-Off Time	T _{off}		0.03	0.2	ms	
Coupled	I/O Isolation Resistance	R _{I/O}	10 ¹⁰			Ω	DC500V
	I/O Capacitance	C _{I/O}		0.8	1.5	pF	f=1MHz

Reference Data

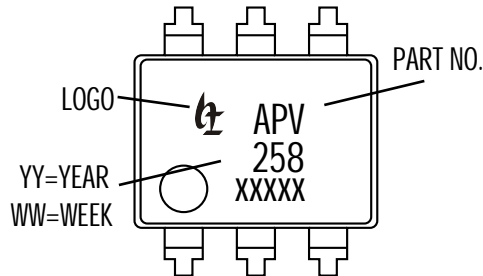


Dimensions

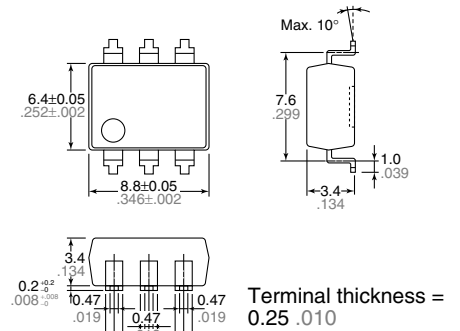
6-SMD



Dimensions
mm inch

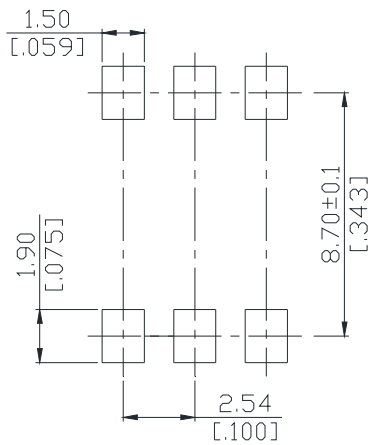


Surface mount terminal type



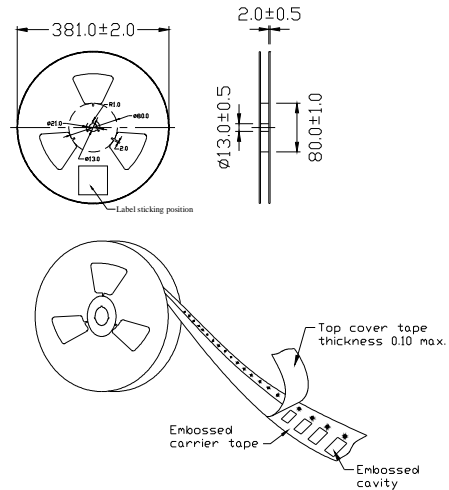
General tolerance: $\pm 0.1 \pm 0.04$

PC board pattern (Top view)

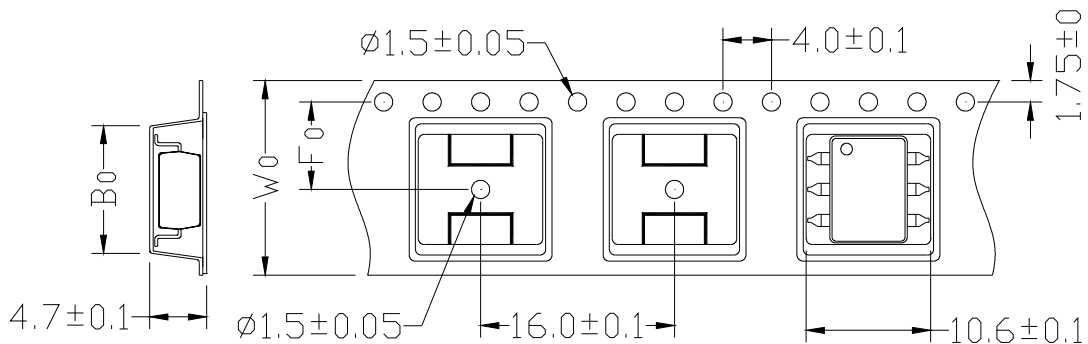


Unit : mm [inch]
Tolerance : ± 0.1

Tape dimensions



Dimensions of tape reel

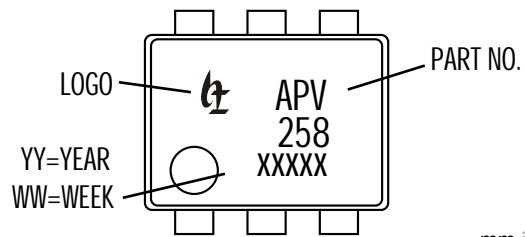
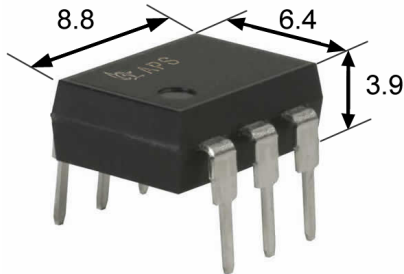


Unit: mm

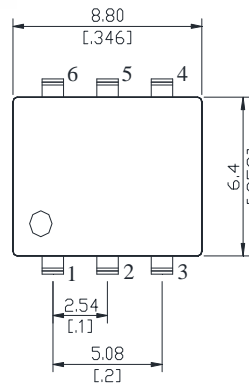
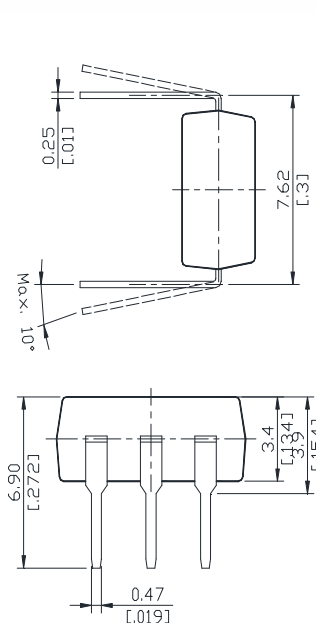
TYPE	B0 ± 0.1	F0 ± 0.1	W0 ± 0.1	13"REEL/PCS
6P	9.4	7.5	16	1000

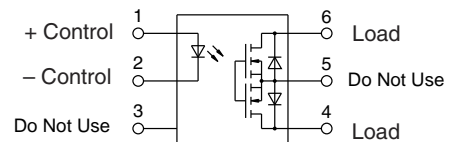
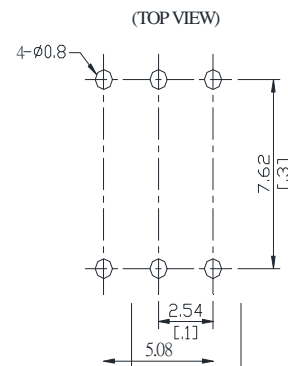
Dimensions
6-DIP

Dimensions

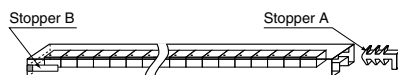


mm inch


 Unit : mm inch
 Tolerance: +0.2 +.007

PC board patter

DIP type

Devices are packaged in a tube so that pin No. 1 is on the stopper B side. Observe correct orientation when mounting them on PC boards.



- Note: 1. There shall be leader of 230 mm minimum which may consist of carrier and or cover tape follower by a minimum of 160 mm of carrier tape sealed with cover tape.
2. There shall be a minimum of 160 mm of empty component pockets sealed with cover tape.
3. Devices are pockets in accordance with EIA standard EIA-481-A and specifications given above.